

Kevin Lauer, Tobias Wittig,
Alexander Lawerenz, Ralf Röder

Defect-engineering of new detector solutions

- 1. Motivation**
- 2. Detectors for low energy electrons**
- 3. Low gain avalanche detectors**
- 4. Conclusion**

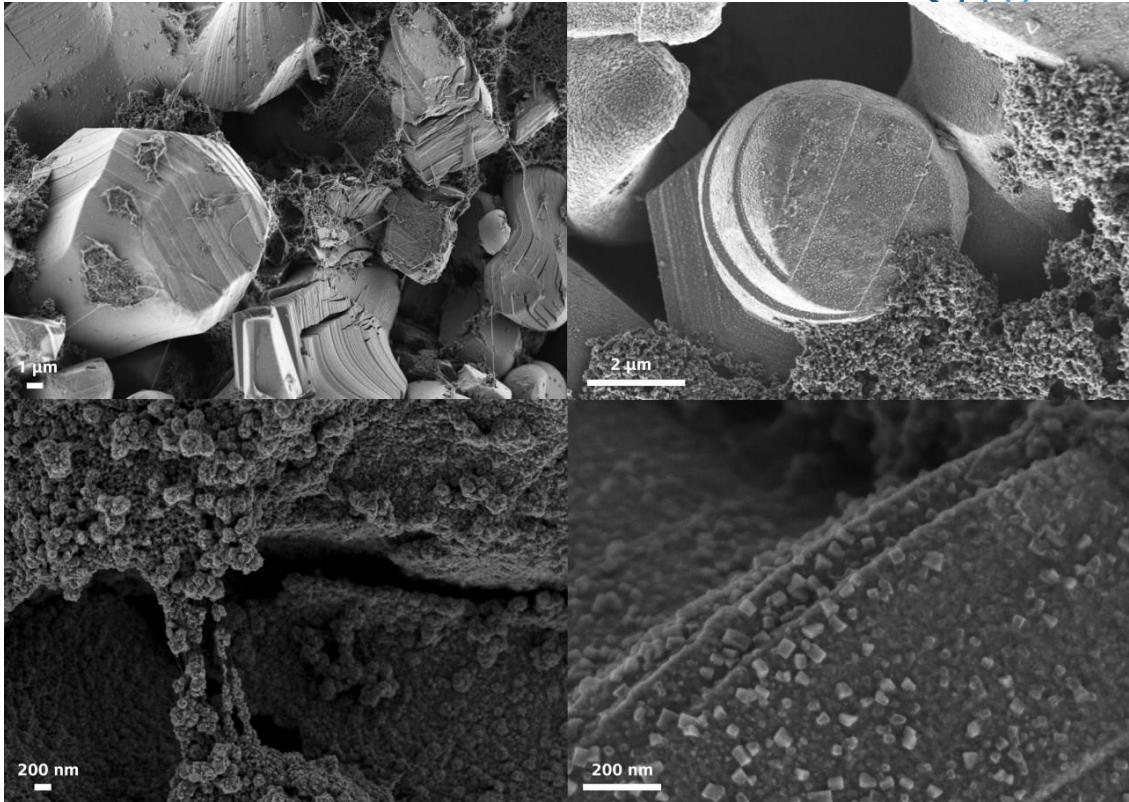
Motivation



- Two projects of CiS are presented:
- I) Development of detectors for low energy electrons
- II) Development of defect-engineering processes to avoid gain layer disappearance in LGAD devices

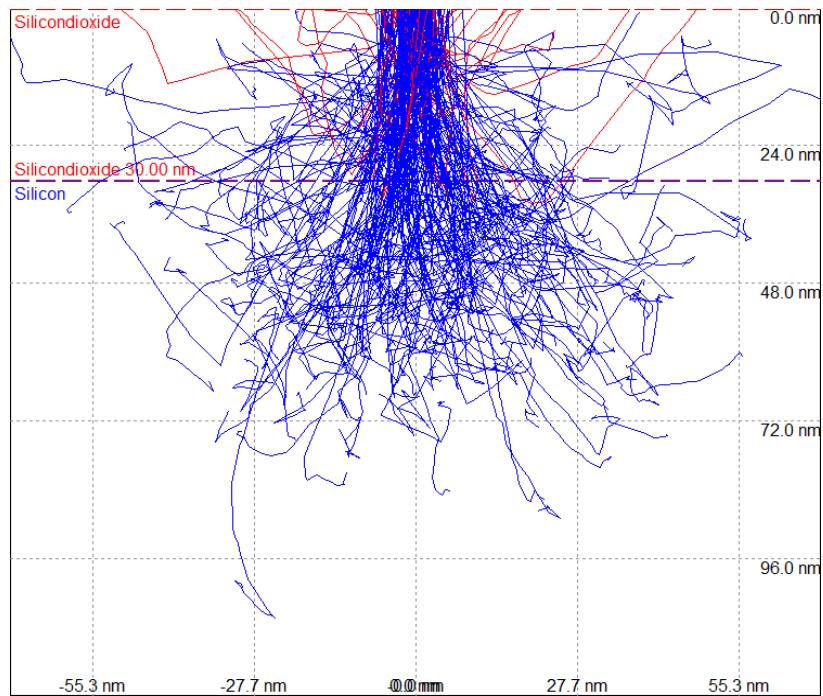
Motivation

- Detection of low energy electrons needed for investigation of sensitive nano structured materials
e.g. for lithium-ion-battery research)
- Low energy electrons increase due to their low penetration depth the surface sensitivity
- Reduction of charging effects



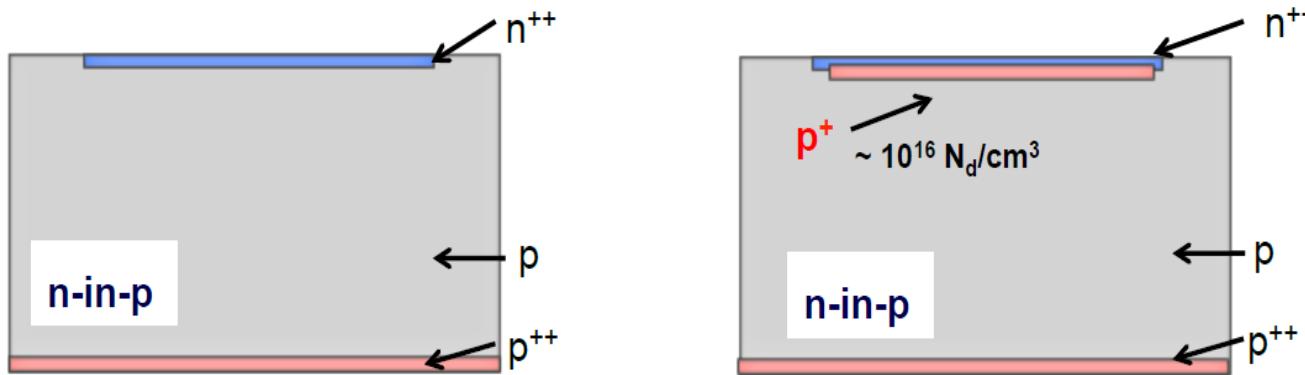
Detection of low energy electrons

- Simulation of 2keV electron beam by SREM
- Penetration depth of low energy electrons in the range of several 10nm
- Development of shallow p-n-junction
- Development of thin entrance window (dead layer)



<http://www.gel.usherbrooke.ca/casino/>

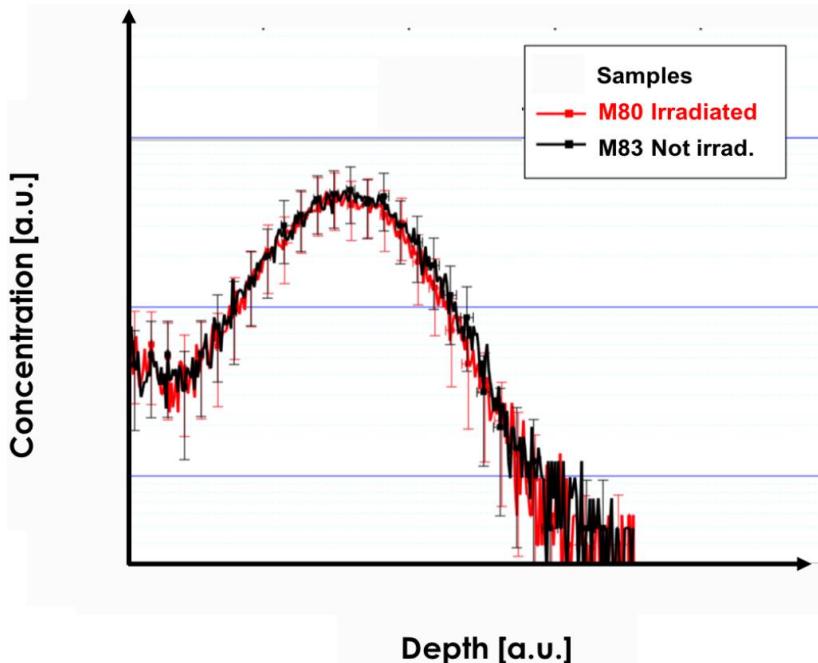
Low gain avalanche detector



N. Cartiglia et al, "Tracking in 4 dimensions", NIMA 845 (2017) 47-51

- p⁺ gain layer below n⁺⁺ region
- p⁺ gain layer adjusted to generate gain of about 20 (10 ... 30) compared to standard n-in-p detector
- Problem: gain layer disappears under irradiation and hence gain disappears

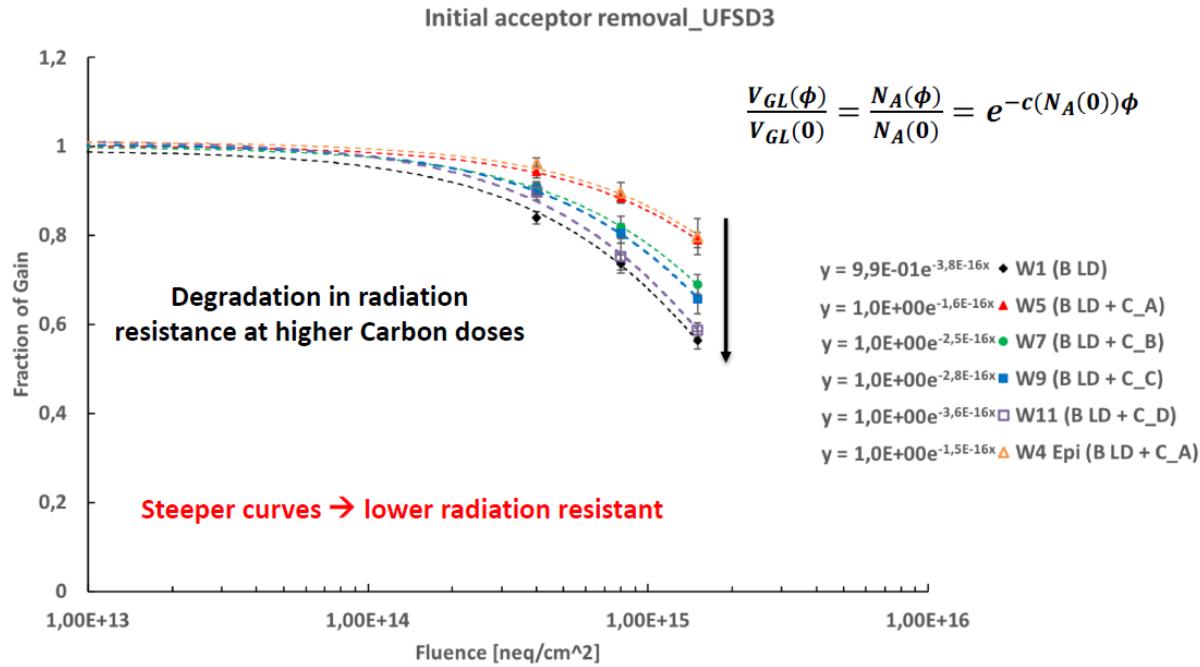
SIMS measurement of gain layer



M. Ferrero et al., NIMA 919, 16 (2019).

- Boron atoms of p^+ gain layer still at same depth
- SIMS measurement shows no difference before and after irradiation
- But boron atoms not electrically active
- Which defect reactions take place?
- **Project goal:**
Stabilizing gain factor by defect-engineering

Approaches for solution of problem



M. Ferrero et al., NIMA 919, 16 (2019).

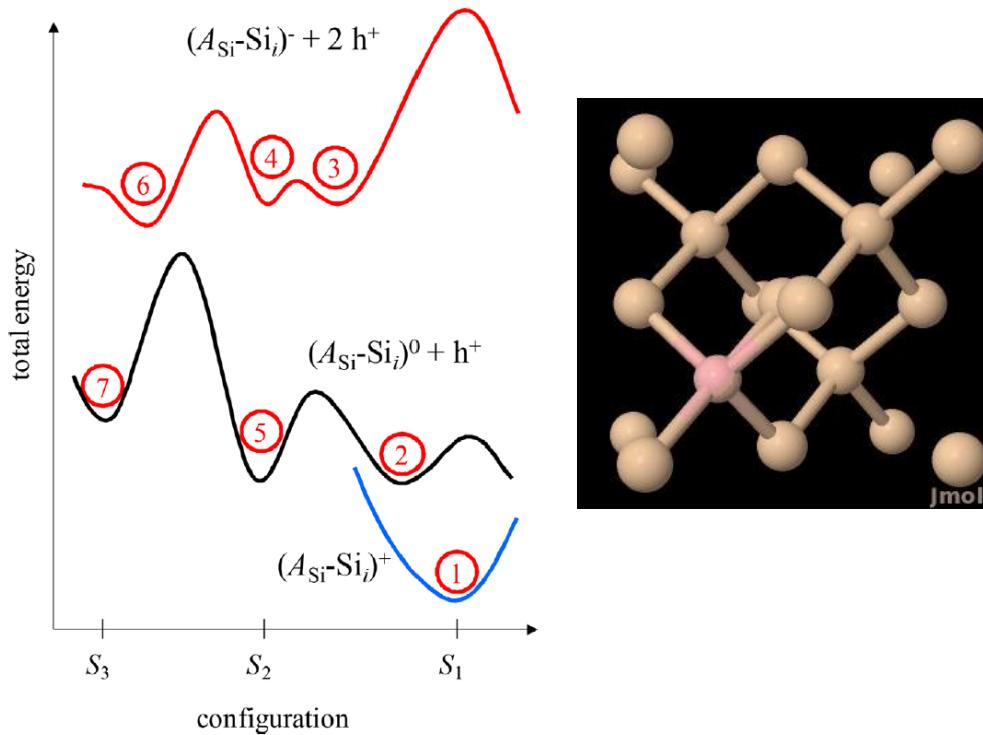
- Co-implantation of carbon, oxygen, nitrogen, ...
- Implantation of alternate acceptors like Indium
- First results promising:
(DeSiD: MF140178)
- DELGAD



Multiplication layer

- Check / map
the homogeneity of the dopant distribution

Explanation approach, $A_{\text{Si}}\text{-Si}_i$ defect model



- Understanding of ongoing defect reactions
- $A_{\text{Si}}\text{-Si}_i$ defect exists in three configurations
- Seven states can be occupied
- Pairing of a substitutional boron atom with an silicon interstitial atom shifts defect from acceptor to donor behavior
- Could explain disappearance of gain layer

K. Lauer et al., Physica Status Solidi (c) 14, 1600033 (2017).

Charateization



- SIMS
- REM/FIB
- scanning acoustic microscopy (SAM)
- Raman microscopy
- transient current technique TCT
- dopant activation:
low-temperature photoluminescence measurements TTPL

Conclusion



- Development of silicon detectors for low energy electrons
- Necessary for enhanced surface sensitive SEM
- Low gain avalanche detectors suffer from disappearance of gain layer due to irradiation
- SIMS results show no removal of boron atoms
- Defect reactions take place
- One possible candidate: formation of $A_{Si}-Si_i$ defect
- Defect-engineering necessary to stabilize gain layer

see also



- K. Lauer, X. Xu, D. Karolewski, U. Gohs, M. Kwestarz, P. Kaminski, R. Täschner, T. Klein, T. Wittig, R. Röder, and T. Ortlepp, „Impact of Electron Irradiation on N- and O-Enriched FZ Silicon p-in-n Pad Radiation Detectors“, *Physica Status Solidi (c)* 14, 1700019 (2017).
- K. Lauer, C. Möller, C. Teßmann, D. Schulze, and N. V. Abrosimov, “Activation energies of the InSi-Sii defect transitions obtained by carrier lifetime measurements,” *physica status solidi (c)*, vol. 14, no. 5, p. 1600033, 2017.
- Kevin Lauer, Stefan Krischok, Thomas Klein, Mario Bähr, Alexander Lawerenz, Ralf Röder, Thomas Ortlepp, and Uwe Gohs
Light-induced degradation in annealed and electron irradiated silicon: BO-LID effect

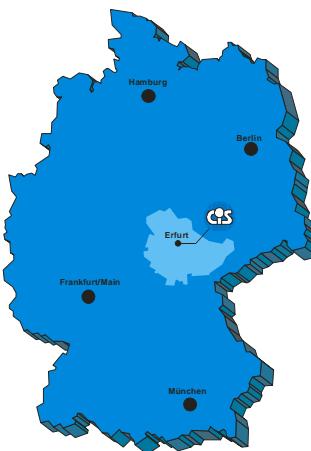
5th anniversary of CiS detector workshop

FuTuRe 2019



2th ... 3th of December 2019, Erfurt, Germany

Workshop on the Future of Silicon Detector Technologies
Big Science Instrumentation and New Markets



Trends in Technologies and Components

TOPs

- Technologies for Quantum photonic components
- New detector solutions for High-Energy and Heavy-Ion physics
- Modelling, Simulation and Analysis of semiconductor behavior (defects in silicon)
- Connecting and assembly techniques esp. UBM, alternative metal layer deposition, pillars, soldering, ...
- Alternative Technology Approaches

Thank you for your kind attention!



Konrad-Zuse-Str. 14
99099 Erfurt, Germany
www.cismst.de

Telefon: +49 361 6631410
Telefax: +49 361 6631413
E-Mail: info@cismst.de

© 2019 CiS Forschungsinstitut für Mikrosensorik GmbH
Copyright: All rights, especially the right of reproduction
and distribution as well as translation, are reserved.